REMARKS

Claim 1 is currently pending in the application; with claim 1 being independent. Claim 1 was pending prior to the Office Action. Claim 1 has been amended.

The Examiner is respectfully requested to reconsider the rejections in view of the amendments and remarks set forth herein. Applicant respectfully requests favorable consideration thereof in light of the amendments and comments contained herein, and earnestly seeks timely allowance of the pending claims.

Claim Rejections – 35 USC § 103

The Examiner rejected claim 1 under 35 U.S.C. § 103(a) as being unpatentable over US 6,040,612 ("Minami et al.") in view of US 7,138,695 ("Kim et al."). Applicant traverses this rejection.

Applicant has amended claim 1 to recite wherein the concave portion forms a clearance between a first adhesion area and a second adhesion area, the first adhesion area being between the solid state image sensor and the cover glass, and the second adhesion area being between the cover glass and the circuit board, wherein the first adhesion area and the second adhesion area are on a same side of the cover glass.

To establish a *prima facie* case of obviousness, the Examiner has the burden of meeting the basic criterion that the prior art must teach or suggest all of the claim limitations.

Regarding this basic criterion, the Applicant submits that Minami et al. and Kim et al. do not disclose or suggest that a concave portion forms a clearance between a first adhesion area and a second adhesion area, the first adhesion area being between the solid state image sensor and the cover glass, and the second adhesion area being between the cover glass and the circuit board, wherein the first adhesion area and the second adhesion area are on a same side of the cover glass.

Minami et al. merely discloses an image pickup apparatus including a conductor lead formed on a terminal of a CCD so as to protrude from the outer periphery of the main frame of an image pickup device body in accordance with a TAB (Tape Automated Bonding) method capable of realizing mass production. A cover glass is set so that an air gap is formed between

the CCD and its image pickup plane side, and thereby an image pickup device body is formed. Moreover, the image pickup device body is set to an aperture of a circuit board to connect the conductor lead to a terminal at the circuit board side (Abstract).

The Examiner pointed to an adhesion area on the left side in Fig. 1D and to an adhesion area on the right side in Fig. 1D, and stated (page 3 of Office Action) that a space between holes 25 and 24A in Fig. 1D of Minami et al. allegedly forms a clearance between an adhesion area between a solid state sensor 20 and a cover glass 22, and an adhesion area between the cover glass 22 and a circuit board 24. Claim 1, however, recites that a concave portion forms a clearance between a first adhesion area and a second adhesion area, the first adhesion area being between the solid state image sensor and the cover glass, and the second adhesion area being between the cover glass and the circuit board, wherein the first adhesion area and the second adhesion area are on a same side of the cover glass. In Fig. 1D of Minami et al., there is no clearance between adhesion areas on a same side of the cover glass 22. For example, in Fig. 1D, there is no clearance between adhesion areas located on the right side of cover glass 22, and formed between CCD 20 and cover glass 22, and above circuit board 24, respectively. Kim et al. merely discloses a method for packaging a pickup device including the steps of forming a printed circuit of a predetermined pattern on an upper surface of a transparent medium, forming a first bump and a second bump on the upper surface of the transparent medium, first bonding the first bump with a pattern of an image chip so as to be electrically connected to each other, secondly bonding the second bump with a circuit of a flexible PCB so as to be electrically connected to each other, and molding a rear surface of the flexible PCB, on which an image chip is mounted, by means of epoxy resin (Abstract). Kim et al. does not show a clearance between a first adhesion area and a second adhesion area, the first adhesion area being between the solid state image sensor and the cover glass, and the second adhesion area being between the cover glass and the circuit board, wherein the first adhesion area and the second adhesion area are on a same side of the cover glass. In Fig. 4, for example, there is no clearance between bumps 14 and 13 (Applicant does not admit that these are adhesion areas) located on a same side of the transparent medium 18.

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Hence, Minami et al. and Kim et al. fail to teach or suggest all of the elements for claim 1.

For all of the above reasons, taken alone or in combination, Applicant respectfully requests reconsideration and withdrawal of the 35 U.S.C. § 103(a) rejection.

Conclusion

In view of the above amendments and remarks, this application appears to be in condition for allowance and the Examiner is, therefore, requested to reexamine the application and pass the claims to issue.

Should there be any outstanding matters that need to be resolved in the present application, the Examiner is respectfully requested to contact the undersigned at telephone number (703) 205-8000, which is located in the Washington, DC area.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. §§ 1.16 or 1.17; particularly, extension of time fees.

Dated: August 25, 2008

Respectfully submitted,

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